### PDF/SOLUTIONS® 2025 Users Conference

# PDF Solutions Equipment and Fab Integration Solutions

Secure, Remote Equipment Connectivity and Control

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#### **PDF Tech Strategy**

**Patrick Pannese** 

#### Over 400 Customers Using Cimetrix Software Including...











































Veeco

































SPTS)





Nikon





#### **Broad Market Adoption**

Last year PDF Cimetrix equipment software was installed on over 7,600 systems

This year over 8,000 semiconductor systems will ship with PDF equipment software including...

- Metrology
- ALD/EPI/Etch
- Pick & Place
- Cleaning/Strip
- Backend Test
- MOCVD & PVD

- Inspection
- Bonding
- Photovoltaic
- Electrochemical Deposition
- Ion Implant
- Lithography

\*The largest OEM in this industry shipped their software on approximately 6k pieces of equipment

#### **Equipment Software Product Portfolio**

	Product Family		Product/Platform	Interface(s)
	Equipment	Connectivity	EquipmentConnect	GEM
				GEM 300
				EDA
		Control	<b>EquipmentControl Foundation</b> (ECF)	GEM, GEM300, EDA
	OEM/OSAT/Factory	Secure Connectivity	secureWISE Agent	IP-SEC VPN Double Encrypted
	Applications		DEEP, Studio Twin, CIM142	gRPC

#### Cutting-Edge Solutions for Semiconductor Innovation

#### Built on 25 years of proven connectivity and control experience

#### secureWISE TCS Agent

- The Embedded Foundation for Cloud-Connected Diagnostics, Analytics, and Digital Twins
- Lightweight, equipment-side foundation installed alongside with secureWISE Agent
- Connects OEM equipment securely to PDF's or Customer's cloud-native products
  - AI/ML, Digital Twin, Exensio Manufacturing Analytics & FDC

#### DΣΣΡ

AI/ML to enhance equipment reliability and reduces downtime

#### **Studio Twin**

- Patent pending throughput technology
- Real-time digital replica for predictive maintenance and optimization
- Improves operational efficiency through data-driven insights

#### Cutting-Edge Solutions for Semiconductor Innovation

#### Built on 25 years of proven connectivity and control experience

#### **EquipmentConnect (GEM, GEM300 & EDA)**

- Latest Development Environment .NET 10 with gRPC API
- Linux & Windows Platforms
- One product with multiple, simultaneous protocols
- Enables high-performance secure data channels

#### **EquipmentControl Foundation**

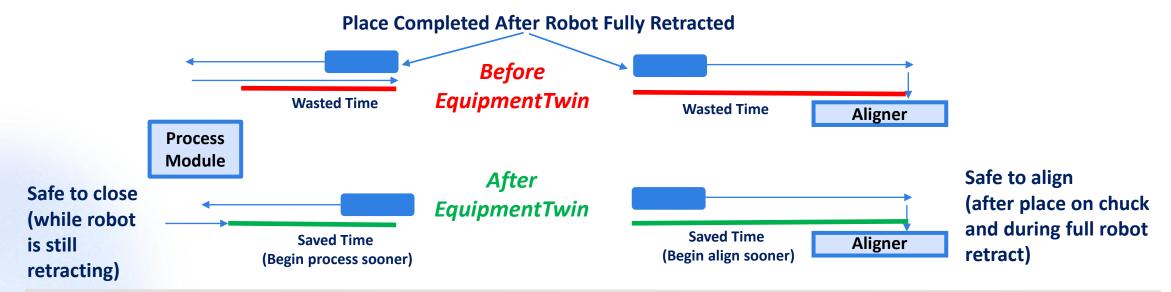
- Latest Development Environment .NET 10 with gRPC API
- Linux & Windows Platforms
- Reuses fully automated GEM/GEM300 EDA test environments

#### Mechanical Throughput Improvement (Patent Pending)

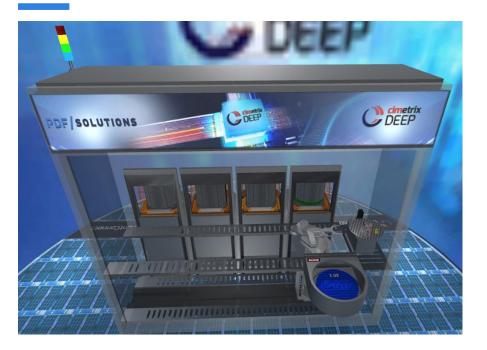
Scenario	Time per Wafer (Seconds)	Throughput (Wafers/Hour)	% Improvement
Original Process	12	300	NA
First Optimization	11	327	9%
Second Optimization	10	360	20%
Significant ET Improvement	8	450	50%

#### Studio Twin's slot valve / aligner optimizations

- Even 2 seconds per move improvement results in significant throughput improvement (20%)
- increased production capacity
- reduced cost of ownership



#### Throughput Optimization - "Dual Align" Process data utilizing Studio Twin



Scenario	Throughput (Wafers/Hour)
Original Process 10.5s Process Dual Align No Optimization	191.83
With EquipmentTwin Technology (Safe To Operate)	204.12
Throughput Improvement	12.29

Potential Fab ROI		
\$6,000 / wafer	\$1.77M / Day	
\$12,000 / wafer	\$3.54M / Day	



OEM Equipment Sales Advantage – Displace competition through higher throughput improvements

**Throughput Gain Impact:** 

+12.29 wafers/hour

\$6,000 per wafer → \$74K/hour | \$1.8M/day | \$657M/year

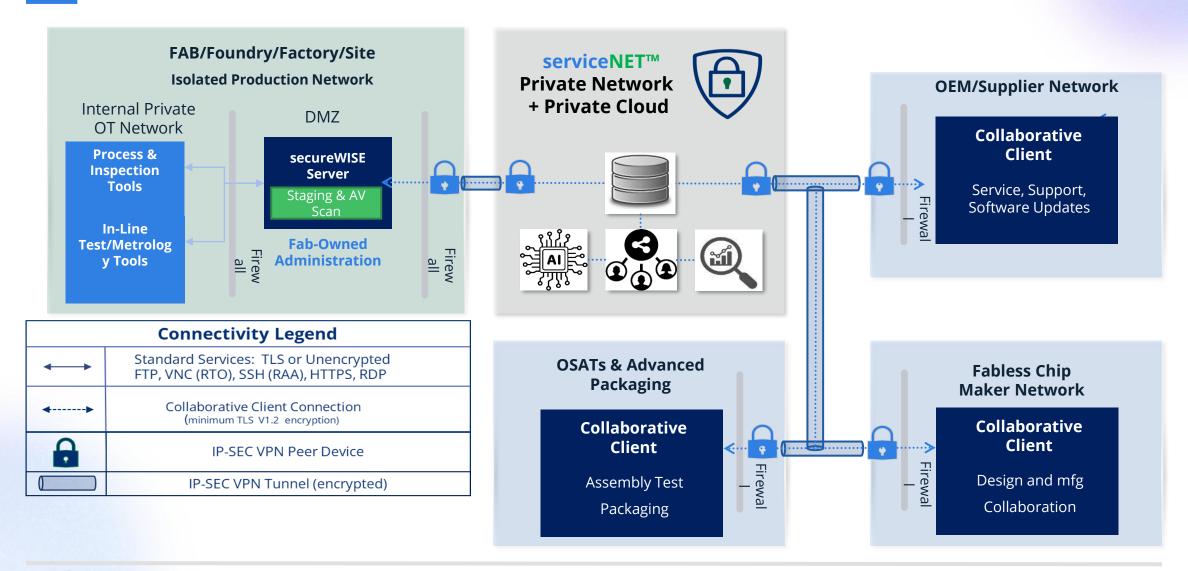
Per tool. Continuous operation. Massive ROI.



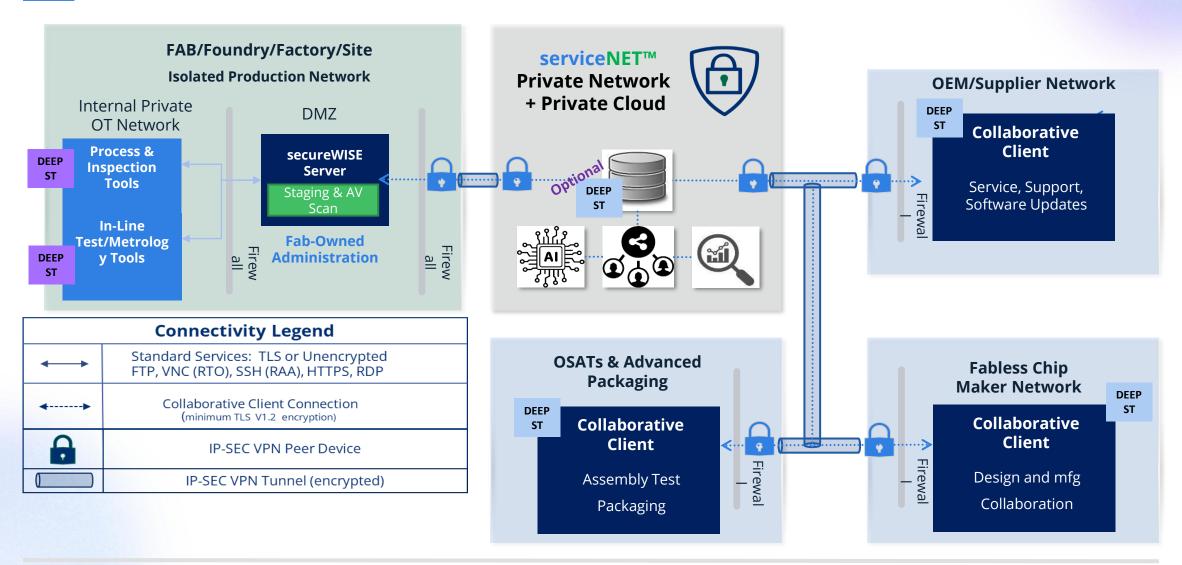
#### **ECF Enhanced with Studio Twin & DEEP!**



#### Secure Private Cloud – Empowered with DEEP & EquipmentTwin



#### Secure Private Cloud – Empowered with DEEP & EquipmentTwin



#### PDF Equipment Software – Value By Customer Type

#### Tier 1 OEMs (AMAT, LAM, TEL, KLA, ASML)

- secureWISE TCS Agent works with internal control software
- Secure, vendor-neutral path into internal AI & Digital Twins or PDF's DEEP + Studio Twin
- TCS Agent roadmap for enhanced cloud analytics

#### Tier 2 /3 OEMs & Emerging Suppliers

- secureWISE TCS Agent Integrated with Cimetrix Connectivity & Control Products
- Instant PDF enhanced analytics with DEEP + Studio Twin capability

#### **Fabs & OSATS**

- Trusted access to equipment intelligence
- Better collaboration with OEMs
- Improved equipment maintenance, yield, and ramp timelines

#### The Equipment Software Stack for the Intelligent Software









Secure Connectivity with Enhanced Insight

Automation Connectivity & Control

Digital Intelligence

AI/ML-driven Resilience

#### PDF/SOLUTIONS°

Cimetrix
StudioTwin™

Demo



## Thank You PDF/SOLUTIONS

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